

TLDCM1513-2-301TF

DC COMMON MODE FILTER

TOP-EMC

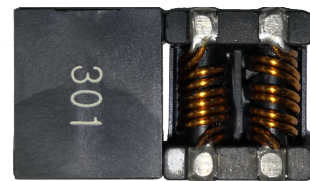
GENERALS

This specification covers the engineering requirements for the (DC Common Mode Filter)

TLDCM1513-2-301TF

FEATURES

- A chip-type common mode filter for large current applications. Common mode impedance surpasses 300 Ω at 100MHz. Noise is greatly suppressed.
- Capable of handling the highest current (up to 15.0A) of any chip-type common mode filter.
- Height and size have been considered, resulting in a compact and light-weight choke coil. Applicable for the miniaturization required to reduce the size and weight of portable equipment.
- The products contain no lead and also support lead-free soldering.
- This product does not contain regulated substances that are slated to be included in RoHS.



APPLICATIONS

Used for power line noise suppression for any electronic devices
Used to counter adapter/battery line noise for relatively large electronic devices such as notebook PCs, stand-alone word processors, etc

TEMPERATURE RANGES

| | |
|----------------------|---------------|
| Operating | -40 to +125°C |
| Storage(After mount) | -40 to +125°C |

Part Number System

TLDCM 1513 -2 -301 T F
① ② ③ ④ ⑤ ⑥

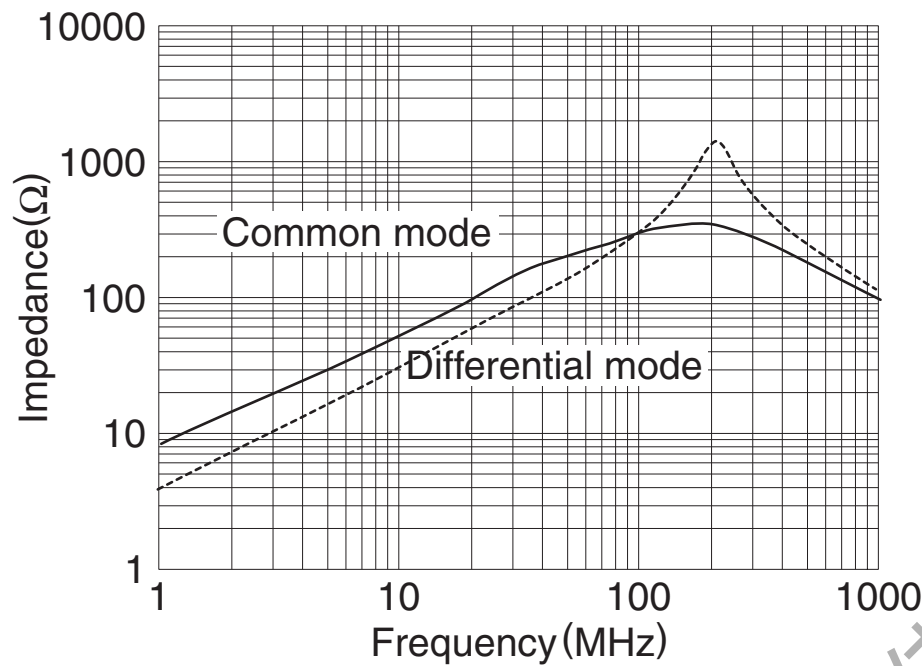
- ① Type:TLDCM
- ② External Dimensions (L×W) (mm) :15.0×13.0mm
- ③ Number of Lines: 2
- ④ Impedance : 301=300 Ω
- ⑤ Packing :Tape & Reel
- ⑥ Hazardous Substance Free Products : F

ELECTRICAL CHARACTERISTICS

| Part No. | Impedance (Ω)[at 100MHz] | DC resistance (m Ω)max. | Rated current Idc(A)max. | Rated Voltage (v)max. | Insulation resistance (M Ω)min. |
|-------------------|-----------------------------------|---------------------------------|--------------------------|-----------------------|---|
| TLDCM1513-2-301TF | 300 (typ) | 3.0 | 15.0 | 80 | 10 |

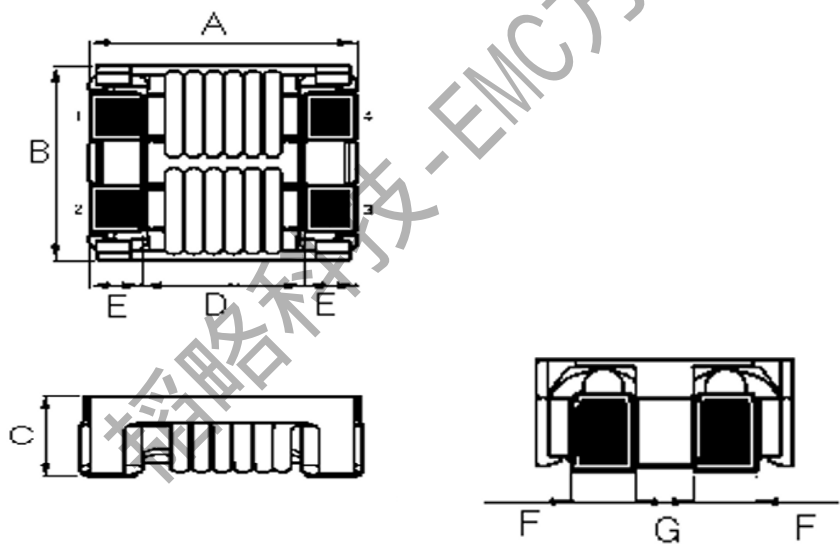
TYPICAL ELECTRICAL CHARACTERISTICS

IMPEDANCE vs. FREQUENCY CHARACTERISTICS



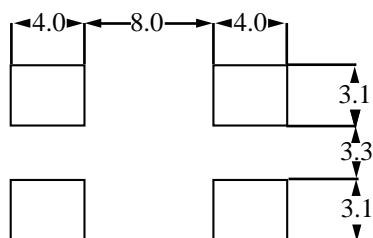
SHAPES AND DIMENSIONS/CIRCUIT DIAGRAM/RECOMMENDED PC BOARD PATTERN(REFLOW SOLDERING)

◆ Dimensions (mm)

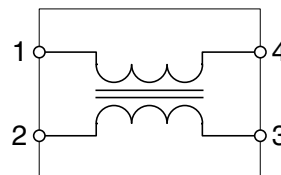


| Product Type | A | B | C | D | E | F | G |
|-------------------|------------|------------|--------|--------|--------|--------|--------|
| TLDCM1513-2-301TF | 15.0 ± 0.5 | 13.0 ± 0.5 | 6.8max | 9.0typ | 3.0typ | 2.7typ | 3.3typ |

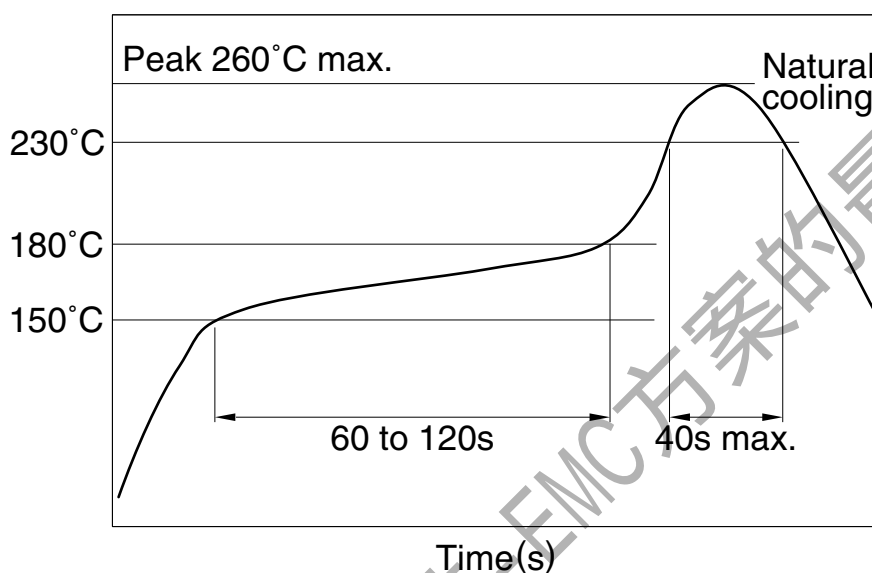
◆ Land Pattern (mm)



◆ Schematics (Bottom)



◆ Reflow Profile For Solder Heat Resistance



CONTACT INFORMATION

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